

CMOS QUAD BILATERAL SWITCH

Check for Samples: [CD4066B-Q1](#)

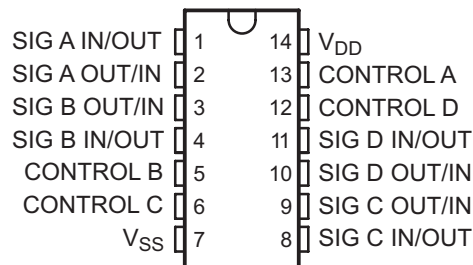
FEATURES

- Qualified for Automotive Applications
- 15-V Digital or ± 7.5 -V Peak-to-Peak Switching
- 125- Ω Typical On-State Resistance for 15-V Operation
- Switch On-State Resistance Matched to Within 5 Ω Over 15-V Signal-Input Range
- On-State Resistance Flat Over Full Peak-to-Peak Signal Range
- High On/Off Output-Voltage Ratio: 80 dB Typical at $f_{is} = 10$ kHz, $R_L = 1$ k Ω
- High Degree of Linearity: <0.5% Distortion Typical at $f_{is} = 1$ kHz, $V_{is} = 5$ V p-p, $V_{DD} - V_{SS} \geq 10$ V, $R_L = 10$ k Ω
- Extremely Low Off-State Switch Leakage, Resulting in Very Low Offset Current and High Effective Off-State Resistance: 10 pA Typical at $V_{DD} - V_{SS} = 10$ V, $T_A = 25^\circ\text{C}$
- Extremely High Control Input Impedance (Control Circuit Isolated From Signal Circuit): 10^{12} Ω Typical
- Low Crosstalk Between Switches: -50 dB Typical at $f_{is} = 8$ MHz, $R_L = 1$ k Ω
- Matched Control-Input to Signal-Output Capacitance: Reduces Output Signal Transients
- Frequency Response, Switch On = 40 MHz Typical
- 100% Tested for Quiescent Current at 20 V

- 5-V, 10-V, and 15-V Parametric Ratings
- Latch-Up Exceeds 100mA per JESD78 - Class I
- Meets All Requirements of JEDEC Tentative Standard No. 13-B, *Standard Specifications for Description of "B" Series CMOS Devices*

APPLICATIONS

- Analog Signal Switching/Multiplexing: Signal Gating, Modulator, Squelch Control, Demodulator, Chopper, Commutating Switch
- Digital Signal Switching/Multiplexing
- Transmission-Gate Logic Implementation
- Analog-to-Digital and Digital-to-Analog Conversion
- Digital Control of Frequency, Impedance, Phase, and Analog-Signal Gain

E, F, M, NS, OR PW PACKAGE
(TOP VIEW)


DESCRIPTION/ORDERING INFORMATION

The CD4066B-Q1 is a quad bilateral switch intended for the transmission or multiplexing of analog or digital signals. It is pin-for-pin compatible with the CD4016B, but exhibits a much lower on-state resistance. In addition, the on-state resistance is relatively constant over the full signal-input range.

The CD4066B-Q1 consists of four bilateral switches, each with independent controls. Both the p and the n devices in a given switch are biased on or off simultaneously by the control signal. As shown in [Figure 1](#), the well of the n-channel device on each switch is tied to either the input (when the switch is on) or to V_{SS} (when the switch is off). This configuration eliminates the variation of the switch-transistor threshold voltage with input signal and, thus, keeps the on-state resistance low over the full operating-signal range.

The advantages over single-channel switches include peak input-signal voltage swings equal to the full supply voltage and more constant on-state impedance over the input-signal range. However, for sample-and-hold applications, the CD4016B is recommended.



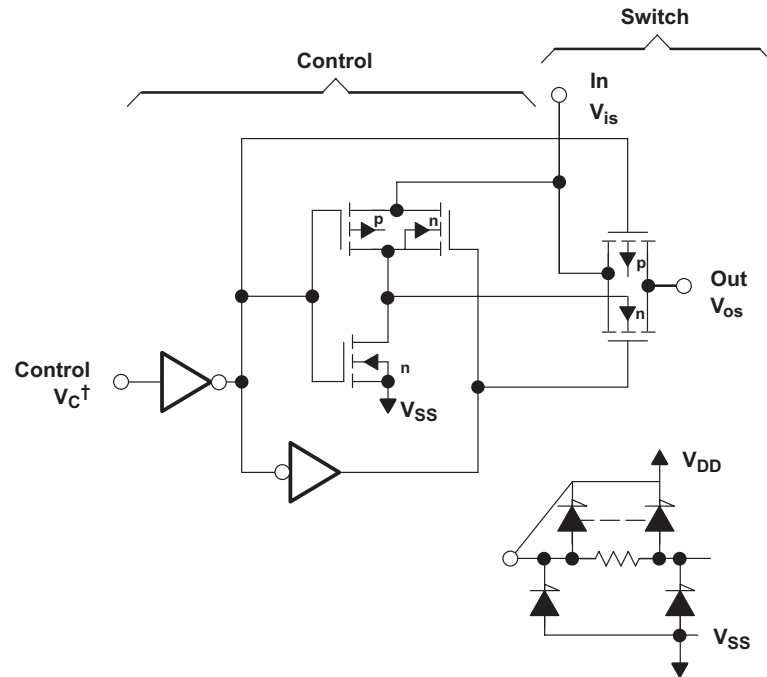
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ORDERING INFORMATION

T _A	PACKAGE		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC – D	Reel of 2500	CD4066BQDRQ1	CD4066BQ



† All control inputs are protected by the CMOS protection network.

NOTES: A. All p substrates are connected to V_{DD}.

B. Normal operation control-line biasing: switch on (logic 1), V_C = V_{DD}; switch off (logic 0), V_C = V_{SS}

C. Signal-level range: V_{SS} ≤ V_{is} ≤ V_{DD}

Figure 1. Schematic Diagram of One-of-Four Identical Switches and Associated Control Circuitry

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		VALUE	UNIT
DC supply-voltage range, V_{DD} (voltages referenced to V_{SS} terminal)		–0.5 to 20	V
Input voltage range, V_{is} (all inputs)		–0.5 to $V_{DD} + 0.5$	V
DC input current, I_{IN} (any one input)		±10	mA
Package thermal impedance, θ_{JA} ⁽²⁾	D package	86	°C/W
ESD Electrostatic discharge ⁽³⁾	Human-Body Model (HBM)	500	V
	Machine Model (MM)	150	
	Field_Induced_Charged Device Model (CDM)	1000	
Lead temperature (during soldering): At distance $1/16 \pm 1/32$ inch ($1,59 \pm 0,79$ mm) from case for 10 s max		265	°C
Storage temperature range, T_{stg}		–65 to 150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The package thermal impedance is calculated in accordance with JESD 51-7.
- (3) Tested in accordance with AEC-Q100.

THERMAL INFORMATION

THERMAL METRIC ⁽¹⁾		CD4066B-Q1	UNITS
		D PACKAGE	
		14 PINS	
θ_{JA}	Junction-to-ambient thermal resistance	92.4	°C/W
θ_{JcTop}	Junction-to-case (top) thermal resistance	52.5	
θ_{JB}	Junction-to-board thermal resistance	46.7	
ψ_{JT}	Junction-to-top characterization parameter	46.4	
ψ_{JB}	Junction-to-board characterization parameter	46.4	
θ_{JcBot}	Junction-to-case (bottom) thermal resistance	N/A	

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT
V_{DD}	Supply voltage	3	18	V
T_A	Operating free-air temperature	–40	125	°C

ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	LIMITS AT INDICATED TEMPERATURES						UNIT
		V _{IN} (V)	V _{DD} (V)	–40°C	125°C	25°C		
						TYP	MAX	
I _{DD} Quiescent device current		0.5	5	0.25	7.5	0.01	0.25	μA
		0.10	10	0.5	15	0.01	0.5	
		0.15	15	1	30	0.01	1	
		0.20	20	5	150	0.02	5	
SIGNAL INPUTS (V_{is}) AND OUTPUTS (V_{os})								
r _{on} On-state resistance (max)	V _C = V _{DD} , R _L = 10 kΩ returned to $\frac{V_{DD} V_{SS}}{2 V_{DD}}$, V _{is} = V _{SS}	5		850	1300	470	1050	Ω
		10		330	550	180	400	
		15		210	320	125	240	
Δr _{on} On-state resistance difference between any two switches	R _L = 10 kΩ, V _C = V _{DD}	5				15		Ω
		10				10		
		15				5		
THD Total harmonic distortion	V _C = V _{DD} = 5 V, V _{SS} = –5 V, V _{is(p-p)} = 5 V (sine wave centered on 0 V), R _L = 10 kΩ, f _{is} = 1-kHz sine wave					0.4%		
3-dB cutoff frequency (switch on)	V _C = V _{DD} = 5 V, V _{SS} = –5 V, V _{is(p-p)} = 5 V (sine wave centered on 0 V), R _L = 1 kΩ					40		MHz
–50-dB feedthrough frequency (switch off)	V _C = V _{SS} = –5 V, V _{is(p-p)} = 5 V (sine wave centered on 0 V), R _L = 1 kΩ					1		MHz
I _{is} Input/output leakage current (switch off) (max)	V _C = 0 V, V _{is} = 18 V, V _{os} = 0 V; and V _C = 0 V, V _{is} = 0 V, V _{os} = 18 V	18		±0.1	±1	±10 ^{–5}	±0.1	μA
–50-dB crosstalk frequency	V _C (A) = V _{DD} = 5 V, V _C (B) = V _{SS} = –5 V, V _{is} (A) = 5 V _{p-p} , 50-Ω source, R _L = 1 kΩ					8		MHz
t _{pd} Propagation delay (signal input to signal output)	R _L = 200 kΩ, V _C = V _{DD} , V _{SS} = GND, C _L = 50 pF, V _{is} = 10 V (square wave centered on 5 V), t _r , t _f = 20 ns	5				20	40	ns
		10				10	20	
		15				7	15	
C _{is} Input capacitance	V _{DD} = 5 V, V _C = V _{SS} = –5 V					8		pF
C _{os} Output capacitance	V _{DD} = 5 V, V _C = V _{SS} = –5 V					8		pF
C _{ios} Feedthrough	V _{DD} = 5 V, V _C = V _{SS} = –5 V					0.5		pF

ELECTRICAL CHARACTERISTICS (continued)

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{IN} (V)	V _{DD} (V)	LIMITS AT INDICATED TEMPERATURES				UNIT
				–40°C	125°C	25°C		
						TYP	MAX	
CONTROL (V_C)								
V _{I_{LC}} Control input, low voltage (max)	I _{is} < 10 mA, V _{is} = V _{SS} , V _{OS} = V _{DD} , and V _{is} = V _{DD} , V _{OS} = V _{SS}	5	10	1	1	1	V	
				2	2	2		
				2	2	2		
V _{I_{HC}} Control input, low voltage	See Figure 6	5	10	3.5 (MIN)		1	V	
				7 (MIN)				
				11 (MIN)				
I _{IN} Input current (max)	V _{is} ≤ V _{DD} , V _{DD} – V _{SS} = 18 V, V _{CC} ≤ V _{DD} – V _{SS}	18		±0.1	±1	±10 ⁻⁵ ±0.1	µA	
Crosstalk (control input to signal output)	V _C = 10 V (square wave), t _r , t _f = 20 ns, R _L = 10 kΩ	10				50	mW	
Turn-on and turn-off propagation delay	V _{IN} = V _{DD} , t _r , t _f = 20 ns, C _L = 50 pF, R _L = 1 kΩ	5	10	15		35	70	ns
						20	40	
						15	30	
Maximum control input repetition rate	V _{is} = V _{DD} , V _{SS} = GND, R _L = 1 kΩ to GND, C _L = 50 pF, V _C = 10 V (square wave centered on 5 V), t _r , t _f = 20 ns, V _{os} = 1/2 V _{os} at 1 kHz	5	10	15		6	9.5	MHz
						9		
						9.5		
C _i Input capacitance						5	pF	

SWITCHING CHARACTERISTICS

V _{DD} (V)	V _{is} (V)	SWITCH INPUT			SWITCH OUTPUT, V _{os} (V)	
		I _{is} (mA)			MIN	MAX
		–40°C	25°C	125°C		
5	0	0.61	0.51	0.36	4.6	0.4
5	5	–0.61	–0.51	–0.36		
10	0	1.5	1.3	0.9		
10	10	–1.6	–1.3	–0.9		
15	0	4	3.4	2.4	13.5	1.5
15	15	–4	–3.4	–2.4		

TYPICAL CHARACTERISTICS

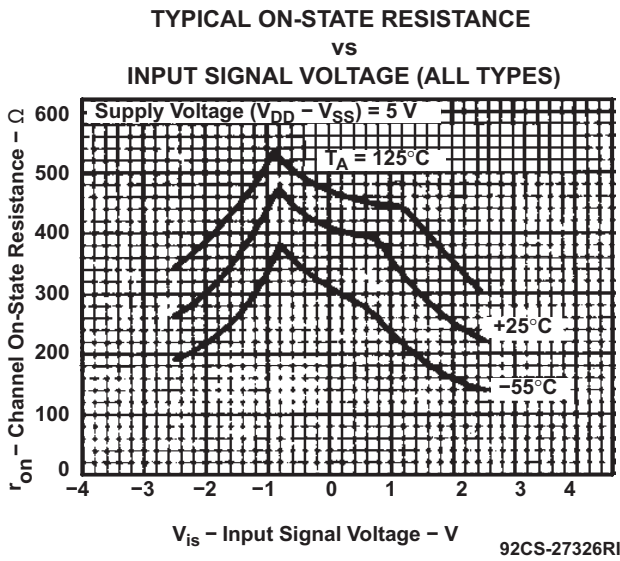


Figure 2.

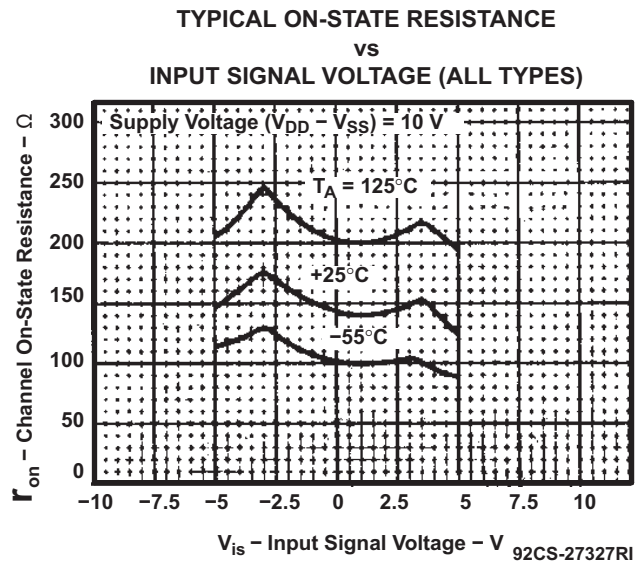


Figure 3.

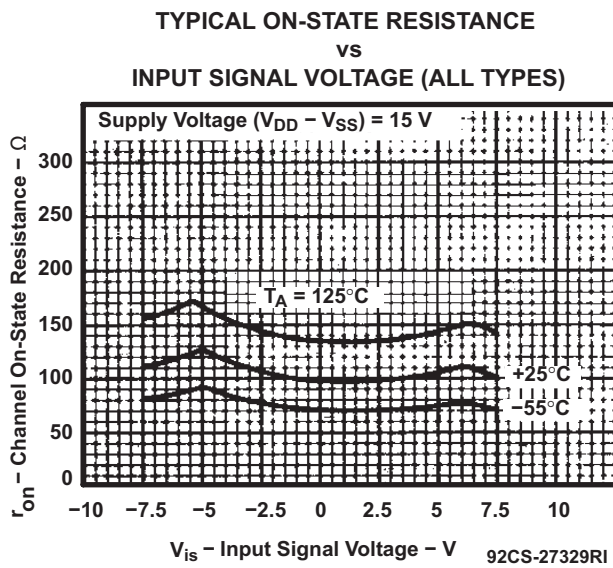


Figure 4.

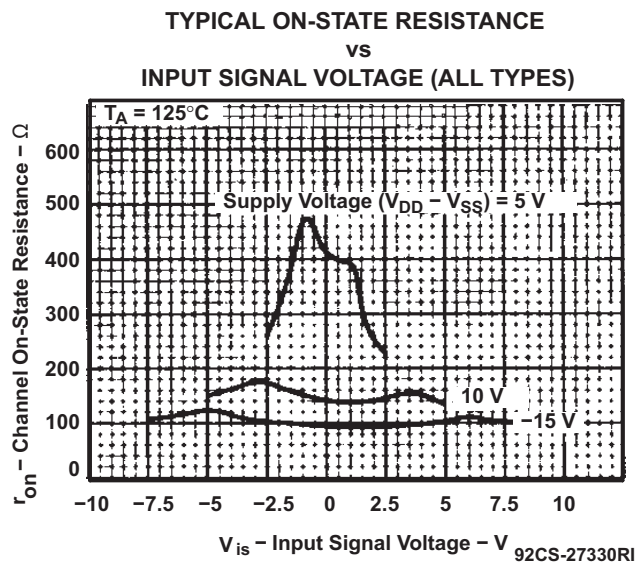
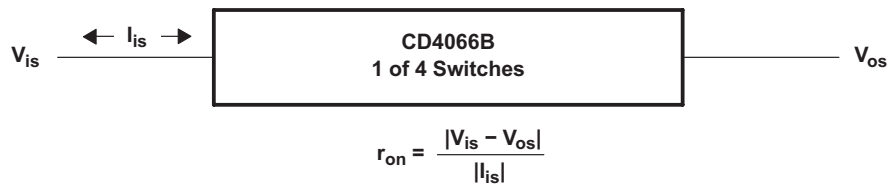


Figure 5.



92CS-30966

Figure 6. Determination of r_{on} as a Test Condition for Control-Input High-Voltage (VIHC) Specification

TYPICAL CHARACTERISTICS (continued)

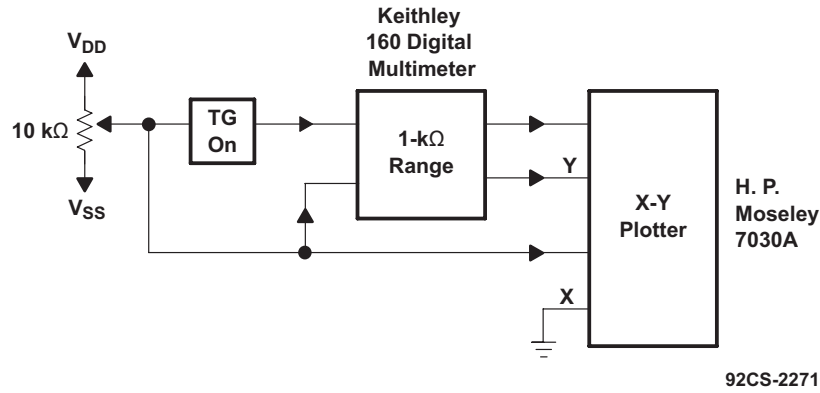


Figure 7. Channel On-State Resistance Measurement Circuit

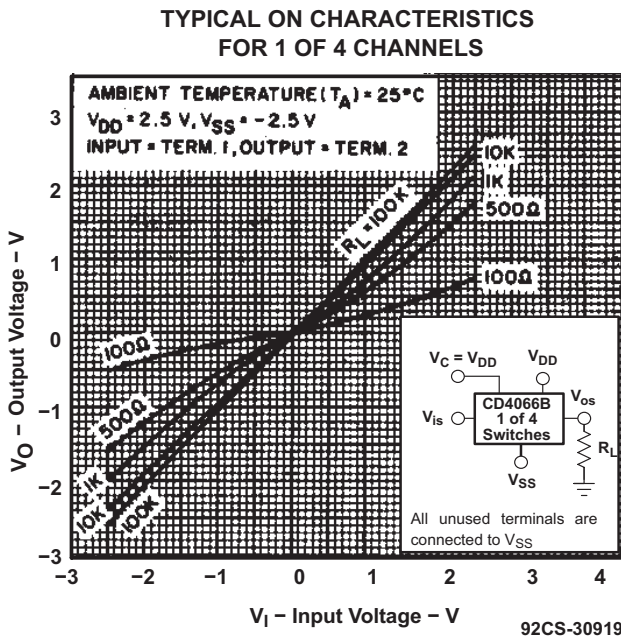


Figure 8.

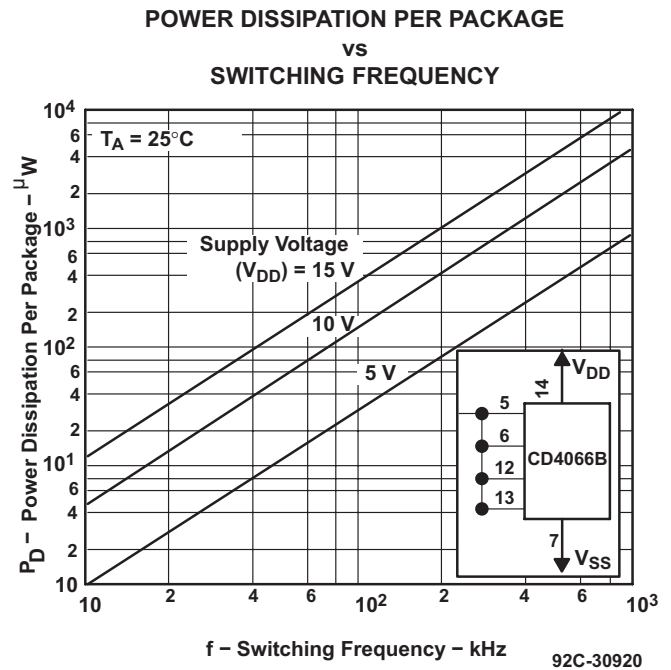
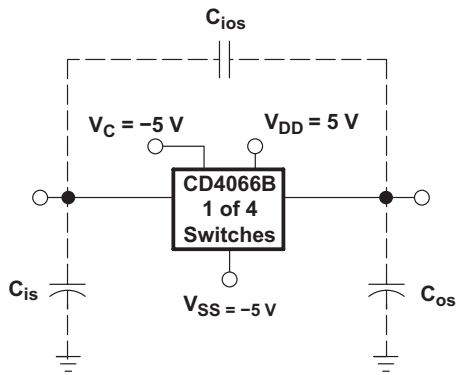


Figure 9.

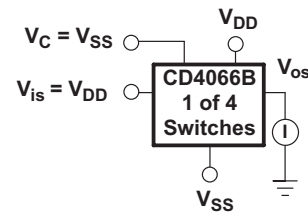
TYPICAL CHARACTERISTICS (continued)



92CS-30921

Measured on Boonton capacitance bridge, model 75a (1 MHz); test-fixture capacitance nulled out.

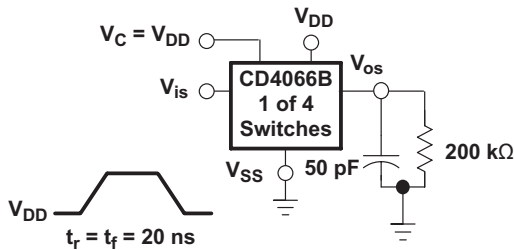
Figure 10. Typical On Characteristics for One of Four Channels



92CS-30922

All unused terminals are connected to V_{SS}.

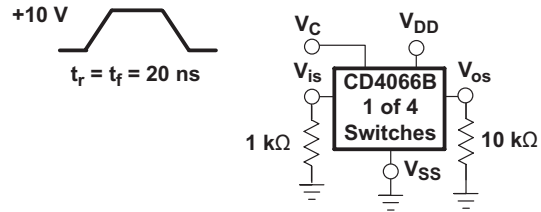
Figure 11. Off-Switch Input or Output Leakage



92CS-30923

All unused terminals are connected to V_{SS}.

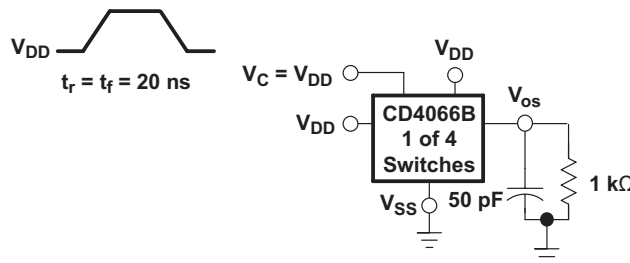
Figure 12. Propagation Delay Time Signal Input (V_{is}) to Signal Output (V_{os})



92CS-30924

All unused terminals are connected to V_{SS}.

Figure 13. Crosstalk-Control Input to Signal Output



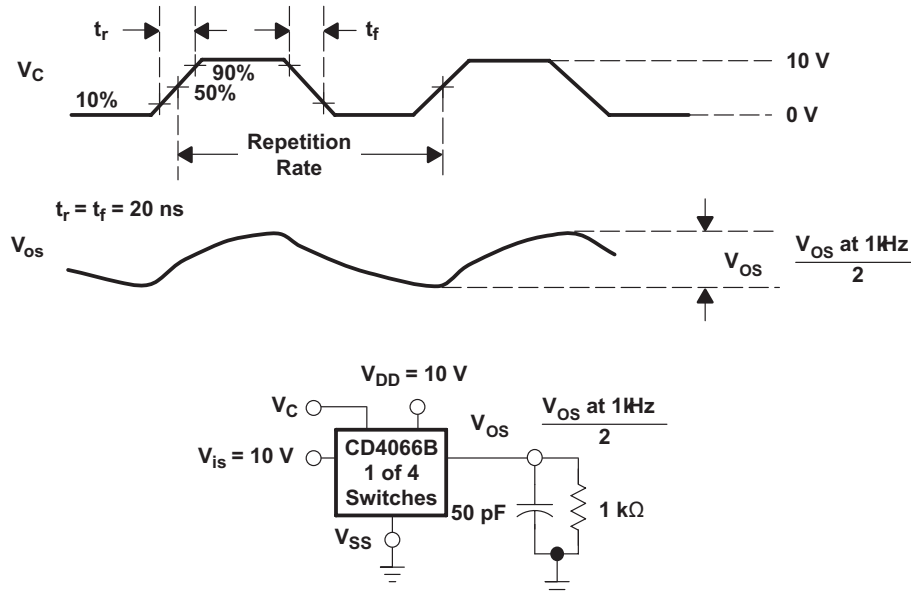
92CS-30925

NOTES: A. All unused terminals are connected to V_{SS}.

B. Delay is measured at V_{os} level of +10% from ground (turn-on) or on-state output level (turn-off).

Figure 14. Propagation Delay, t_{PLH}, t_{PHL} Control-Signal Output

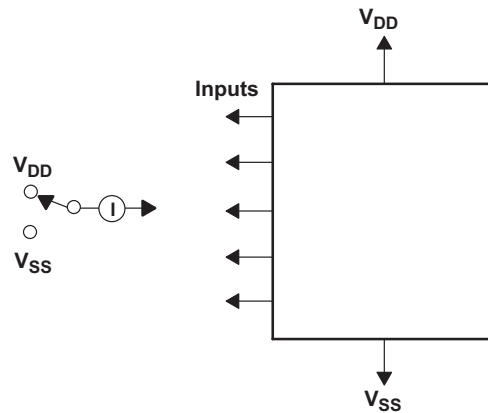
TYPICAL CHARACTERISTICS (continued)



All unused terminals are connected to V_{SS} .

92CS-30925

Figure 15. Maximum Allowable Control-Input Repetition Rate



92CS-27555

Measure inputs sequentially to both V_{DD} and V_{SS} . Connect all unused inputs to either V_{DD} or V_{SS} . Measure control inputs only.

Figure 16. Input Leakage-Current Test Circuit

TYPICAL CHARACTERISTICS (continued)

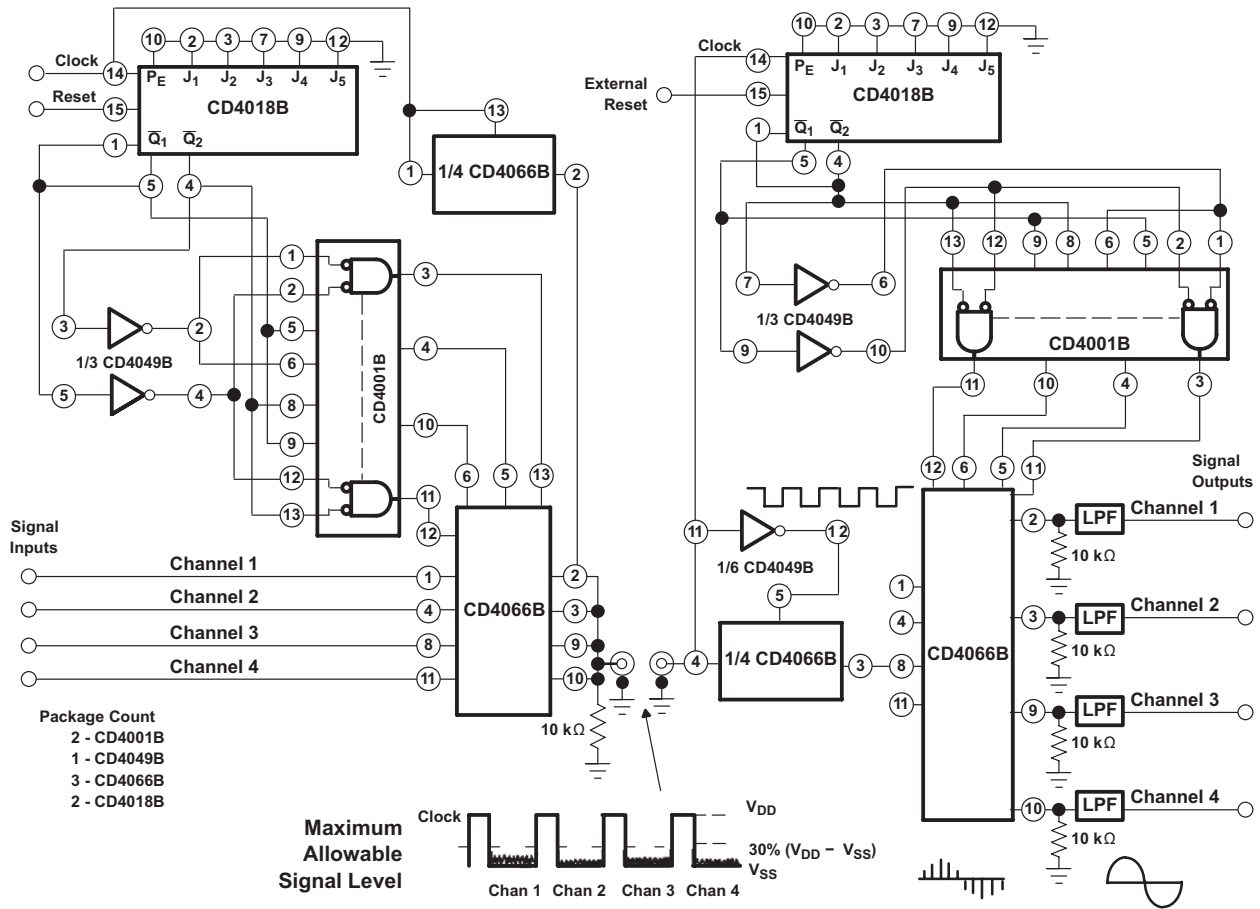


Figure 17. Four-Channel PAM Multiplex System Diagram

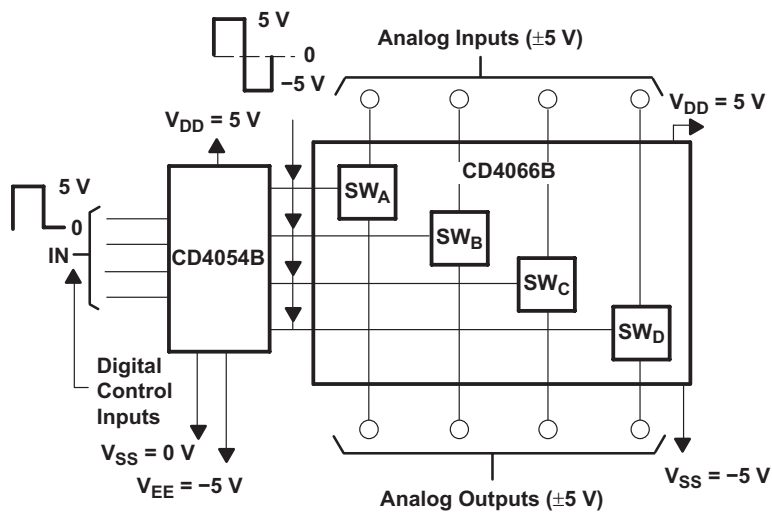


Figure 18. Bidirectional Signal Transmission Via Digital Control Logic

APPLICATION INFORMATION

In applications that employ separate power sources to drive V_{DD} and the signal inputs, the V_{DD} current capability should exceed V_{DD}/R_L (R_L = effective external load of the four CD4066B-Q1 bilateral switches). This provision avoids any permanent current flow or clamp action on the V_{DD} supply when power is applied or removed from the CD4066B-Q1.

In certain applications, the external load-resistor current can include both V_{DD} and signal-line components. To avoid drawing V_{DD} current when switch current flows into terminals 1, 4, 8, or 11, the voltage drop across the bidirectional switch must not exceed 0.8 V (calculated from r_{on} values shown).

No V_{DD} current will flow through R_L if the switch current flows into terminals 2, 3, 9, or 10.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CD4066BQDRQ1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	CD4066BQ	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD4066B-Q1 :

- Catalog: [CD4066B](#)

- Military: [CD4066B-MIL](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040047-5/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com